

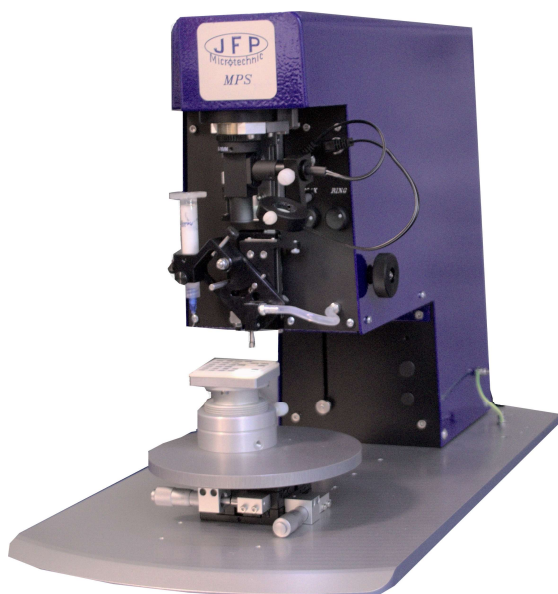
JFP MPS Manual Placer System

The machines which require minimal training to operate



MPS Epoxy Die Bonder

Very High Accuracy
Small Chips & SMD Parts Assembly



- The MPS fulfil accurate Picking and Placement of delicate devices.
- Tool holder design, rocking Head, provides an easy solution for gluing...
- Video Interface compatible for Ultra-HD Camera, with adjustable digital magnification for flexibility, small and large chip sizes.
- A Flip Vision alignment and a true vertical motion achieves high accuracy placement.
- A side camera, provide process vision; camera can be tilted at any angle; high magnification zoom capability for very small devices or critical process.
- MPS is a robust, and reliable mechanical concept, do not requires any training to operate.
- **MPS provides appropriate Platforms for die assembly and small SMD placement**
 - Lab and prototype
 - Small parts handling capability
 - Epoxy dispenser
 - Solder paste
 - SMD Reflow
 - Eutectic die bonding

SYSTEM

- Table Top machine
- Compact system
- Z movement: safe manual drive system
- True Vertical motion
- True vertical Vision, Ultra-HD Camera
- Soft touch-down
- Throat: 200mm, Access for large substrates

DIE & SUBSTRATE

- Minimum component size: 100*100µm
- Vacuum Tool holders
- Substrate, size Up to 350 mm
WafflePack, GelPack...

Workholder Stage

- Manually handled
- Fine motion X&Y Stage,
Travel 25x25 mm, resolution 1µm
- Rotary base for easy Theta adjustments
- Work Height : 100mm or 60mm
- Height adjustable workholders
- Working area : 200x200 mm
- Multi-stage: Pick + Place + stamping Disk
- Heated Stages 50mm (solder-Eutectic)
- Hot Gas Option, for SMD Reflow

VISION-ALIGNMENT SYSTEM

- **Video Microscope:** UHD Camera 5MP, Zoom
Full Field of view: Up to 10mm
- PC, vision interface, USB3
- Digital CrossHairs, adjustable
- LED lightings coaxial and oblique
- **Flip Chip Alignment**
- Video Overlay, face-Up Chip Placement
- Video Overlay, face-Down Chip Placement
for Optional Flip Placement

FEATURES/PARAMETERS

- Low Picking Force: <5 g
- Force range up 500g
- Rocking head, Dispensing/Stamping
- Heated Workholder

APPLICATIONS:

- Lab, Jewelry, Watches, smd, BGA...

OPTIONS :

- Inspection/Process HD Camera
Side view and any angular vision
Zoom: Field of view, FOV= up to 40mm

TECHNICAL SPECIFICATION

Power: 100 / 230VAC 300watt
Vacuum: **integrated in system**
Dimensions: 270*500*352mm
Weight: 17 kg.

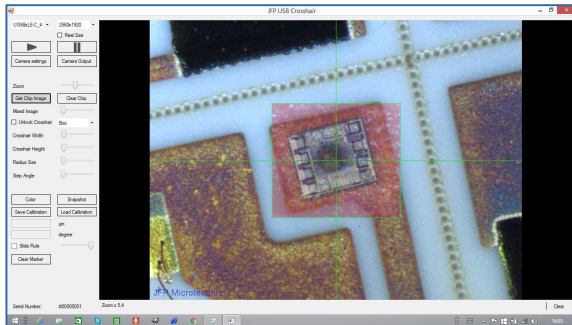
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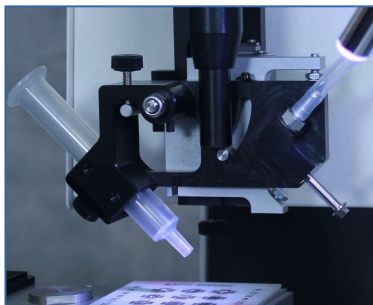
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MPS Options

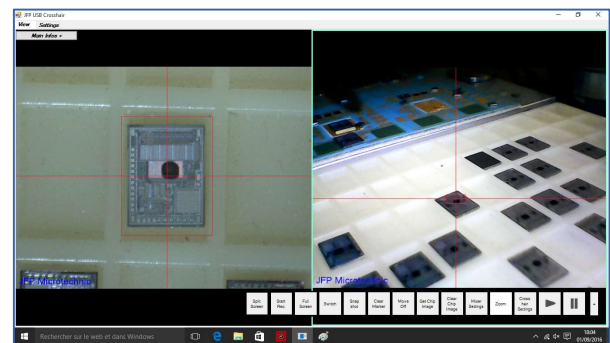


Process Camera



Rocking Head

- Dispenser,
- Stamping,
- Z movement: soft manual drive system
 - Pick & Place
 - Force Adjustment

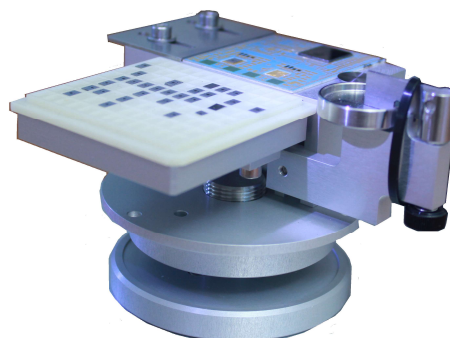


Work Stages

- Micrometric Table,
Accurate micromotion
Fine Theta adjustments
+ Individual chuck
Adjustable Height



- Multi-WH
 - 1 Waffle Pack
 - 2 Place Chuck 2x2",
adjustable height
 - 3 Rotary dish for Stamping



- Heated Chuck 50mm
Reflow, up to 300°C
Adjustable Height

